

### < L/S band internally matched power GaAs FET >

# **MGFS45B2527B**

2.5 - 2.7 GHz BAND / 30W

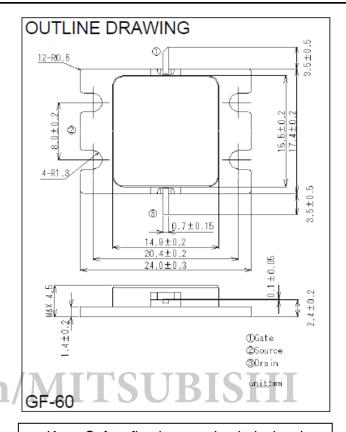
#### **DESCRIPTION**

The MGFS45B2527B is an internally impedance-matched GaAs power FET especially designed for use in 2.5-2.7 GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

#### **FEATURES**

Class AB operation Internally matched to 50(ohm) system

- High output power Po(SAT)=30W (TYP.) @f=2.5 – 2.7GHz
- High power gain GLP=12.5dB (TYP.) @f=2.5 – 2.7GHz
- Distortion
   EVM=1.0% (TYP.) @f=2.5 2.7GHz, Po=34dBm
   EVM=2.0% (TYP.) @f=2.5 2.7GHz, Po=37dBm



# RECOMMENDED BIAS CONDITIONS

• VDS=12V • ID=0.9A • RG=10ohm

#### Absolute maximum ratings (Ta=25°C)

Parameter	Ratings	Unit	
Gate to drain breakdown voltage	-15	V	
Gate to source breakdown voltage	-10	V	
Maximum drain current	10	Α	
Total power dissipation	er dissipation 78		
Cannel temperature	175	°C	
Storage temperature	-55 to +150	°C	
	Gate to drain breakdown voltage Gate to source breakdown voltage Maximum drain current Total power dissipation Cannel temperature	Gate to drain breakdown voltage -15 Gate to source breakdown voltage -10 Maximum drain current 10 Total power dissipation 78 Cannel temperature 175 Storage temperature -55 to +150	

\*1 : Tc=25°C

# Keep Safety first in your circuit designs! Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better

and more reliable, but there is always the possibility that trouble may occur with them.

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#### Electrical characteristics (Ta=25°C)

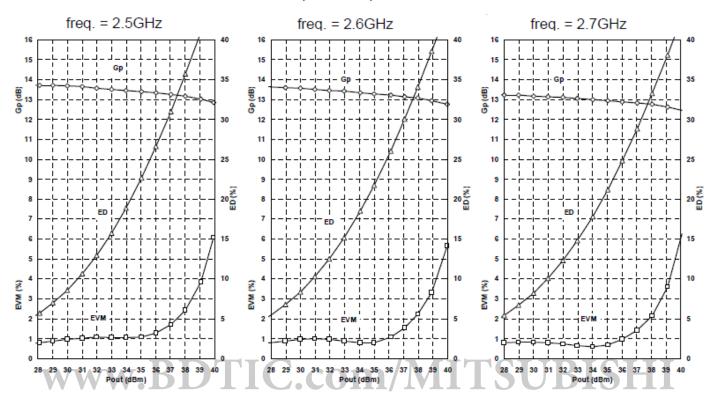
Symbol	Parameter	Test conditions		Limits		Unit
			Min.	Тур.	Max.	
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=100mA	-0.5	-	-3.0	V
Po(SAT)	Output Power	VDS=12V,ID(RF off)=0.9A	-	45	-	dBm
		f=2.5 - 2.7GHz				
GLP	Power Gain	VDS=12V,ID(RF off)=0.9A	10.0	12.5	-	dB
ID	Drain current	f=2.5 - 2.7GHz ,Pout=34dBm	-	1.2	1.5	Α
EVM *2	Error Vector Magnitude		-	1.0	2.0	%
Rth(ch-c) *3	Thermal resistance	delta Vf method	-	1.2	1.9	°C/W

<sup>\*2 :</sup>WiMAX Downlink, 64QAM-3/4, Channel Bandwidth:6MHz

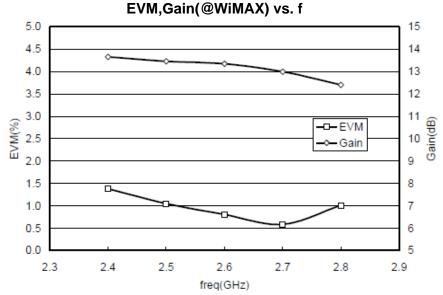
<sup>\*3:</sup> Channel-case

#### MGFS45B2527B TYPICAL CHARACTERISTICS

#### EVM,GP,ED(@WiMAX) vs. Pout

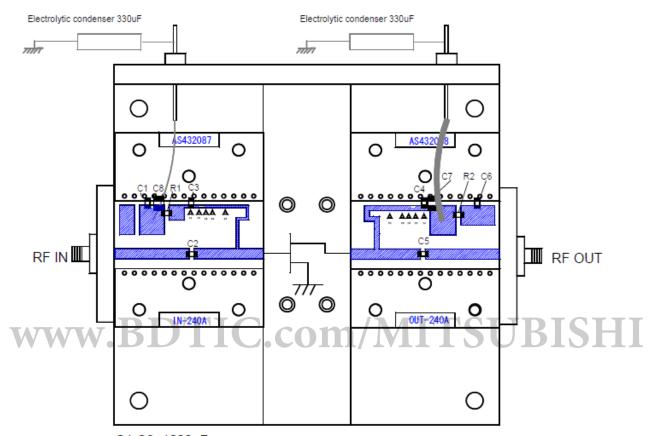


Test Condition Vds=12V,Idq=0.9A,Ta=25deg.C WiMAX:64QAM-3/4,Bw=6MHz



Test Condition
Vds=12V,Idq=0.9A,Pout=34dBm,Ta=25deg.C
WiMAX:64QAM-3/4,Bw=6MHz

#### MGFS45B2527B RF TEST FIXTURE



C1,C6=1000pF

C3,C4=20pF C2,C5=20pF

C7=470nF

C8=100nF

R1=CR10 10ohm

R2=CR10 51ohm

Board material: Teflon, t=0.8mm, Specific dielectric constant=2.6

UNIT:(mm)

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